

MULTI-CHIP SEMICONDUCTOR PACKAGE WITH
INTEGRAL SHIELD AND ANTENNA

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ABSTRACT

10 A transceiver package includes a substrate having an
upper surface. An electronic component is mounted to the
upper surface of the substrate. A shield encloses the
electronic component and shields the electronic component
from radiation. The transceiver package further includes
15 an antenna and a dielectric cap. The dielectric cap is
interposed between the shield and the antenna, the shield
being a ground plane for the antenna.